506350758 11/12/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHIA-YING TIEN	03/30/2015
CHIA-LIN HSUEH	03/30/2015

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
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City:	300-78	
State/Country:	TAIWAN	
Postal Code:	300-78	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17095938

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NAME OF SUBMITTER:	DANIEL R. MCCLURE	
SIGNATURE:	/Daniel R. McClure/	
DATE SIGNED:	11/12/2020	

Total Attachments: 1

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PATENT 506350758 REEL: 054346 FRAME: 0771

ASSIGNMENT

WHEREAS, Chia-Ying T	IEN, and Chia-Lin HSUE	1
		nted certain new and useful improvements as
described and set forth in	the below identified applic	ation for United States Letters Patent:
Title: METHOD AND	SYSTEM FOR CLEAD	NSING WAFER IN CMP PROCESS OF
	ANUFACTURING FABI	77477
Filed: 2015-03-31		l No. <u>14/674,138</u>
Executed on:	NATIONAL PROPERTY OF THE PROPE	
WHEREAS Taiwan Se	miconductor Manufactur	ing Co., Ltd. of No.8, Li-Hsin Road. 6.
		1 300-77, R.O.C. hereinafter referred to as
		interest in the said invention and application
and in any U.S. Letters Pa	tent which may be granted	on the same;
valuable consideration, re sold, assigned and transfe Assignee, and Assignee's the said invention and ap Patent which may hereafte and enjoyed by said Assig said Assignor had this A Letters Patent which may	sceipt of which is hereby a cred, and by these presents successors and assigns, all plication and all future im er be granted on the same i gnee as fully and exclusive ssignment and transfer no	Y CONCERN: Be it known that, for good and teknowledged by Assignor, Assignor has/have a does/do sell, assign and transfer unto the said his/her/their rights, title and interest in and to provements thereon, and in and to any Letters in the United States, the said interest to be held by as it would have been held and enjoyed by t been made, to the full end and term of any any division, renewal, continuation in whole or nor extension thereof.
but at Assignee's expense applications, execute, ve applications for Letters I transfer thereof, and will maintain Letters Patent : Assignee, or Assignee's su	e, cooperate with Assigned erify, acknowledge and Patent and for the reissue perform such other acts a for said invention and in accessors and assigns.	e/they will, without charge to said Assignee, in the prosecution of said application and/or deliver all such further papers, including thereof, and instruments of assignment and s Assignee lawfully may request, to obtain or approvement, and to vest title thereto in said ave signed his/her/their name(s) on the date(s)
03/30/2015		
Date	Name: Chia-Ying TÆN	(Last name: TIEN)
03/30/2015	Chialin Hon	eh.
Date	Name: Chia-Lin HSUEI	H (Last name: HSUEH)

P20141420US00/0503-A39579-US

RECORDED: 11/12/2020

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